



Integrity Server Products and Futures



Ric Lewis

Director, Product Planning and Strategy
Business Critical Systems
Hewlett-Packard

© 2004 Hewlett-Packard Development Company, L.P.
The information contained herein is subject to change without notice





Agenda

- Integrity/Itanium Strategy
- PA-Risc & Alpha Transition
- Integrity Product Lineup
- Integrity Platform Futures



Agenda

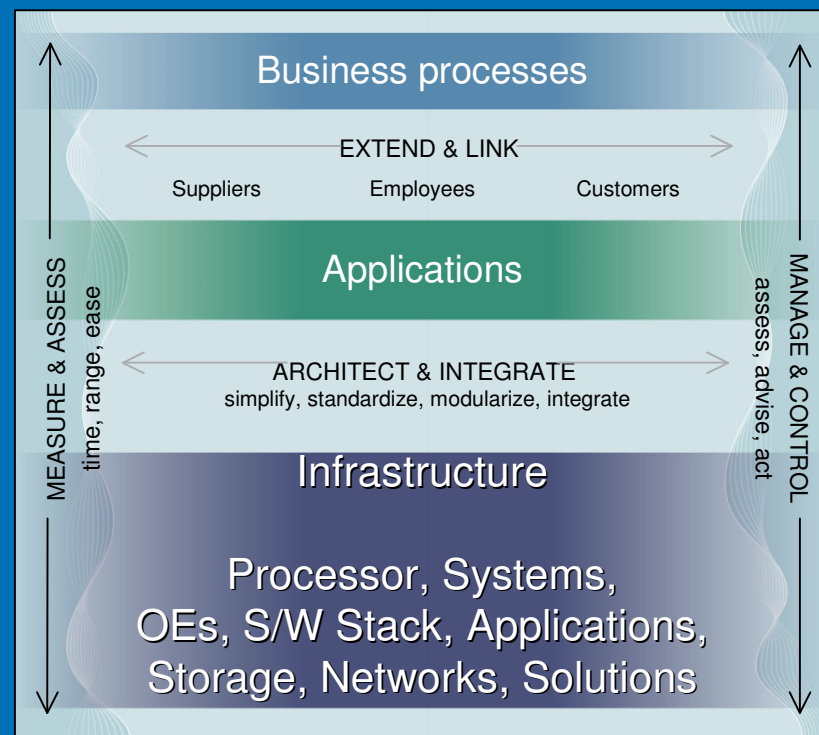
- Integrity/Itanium Strategy
- PA-Risc & Alpha Transition
- Integrity Product Lineup
- Integrity Platform Futures

The next big thing

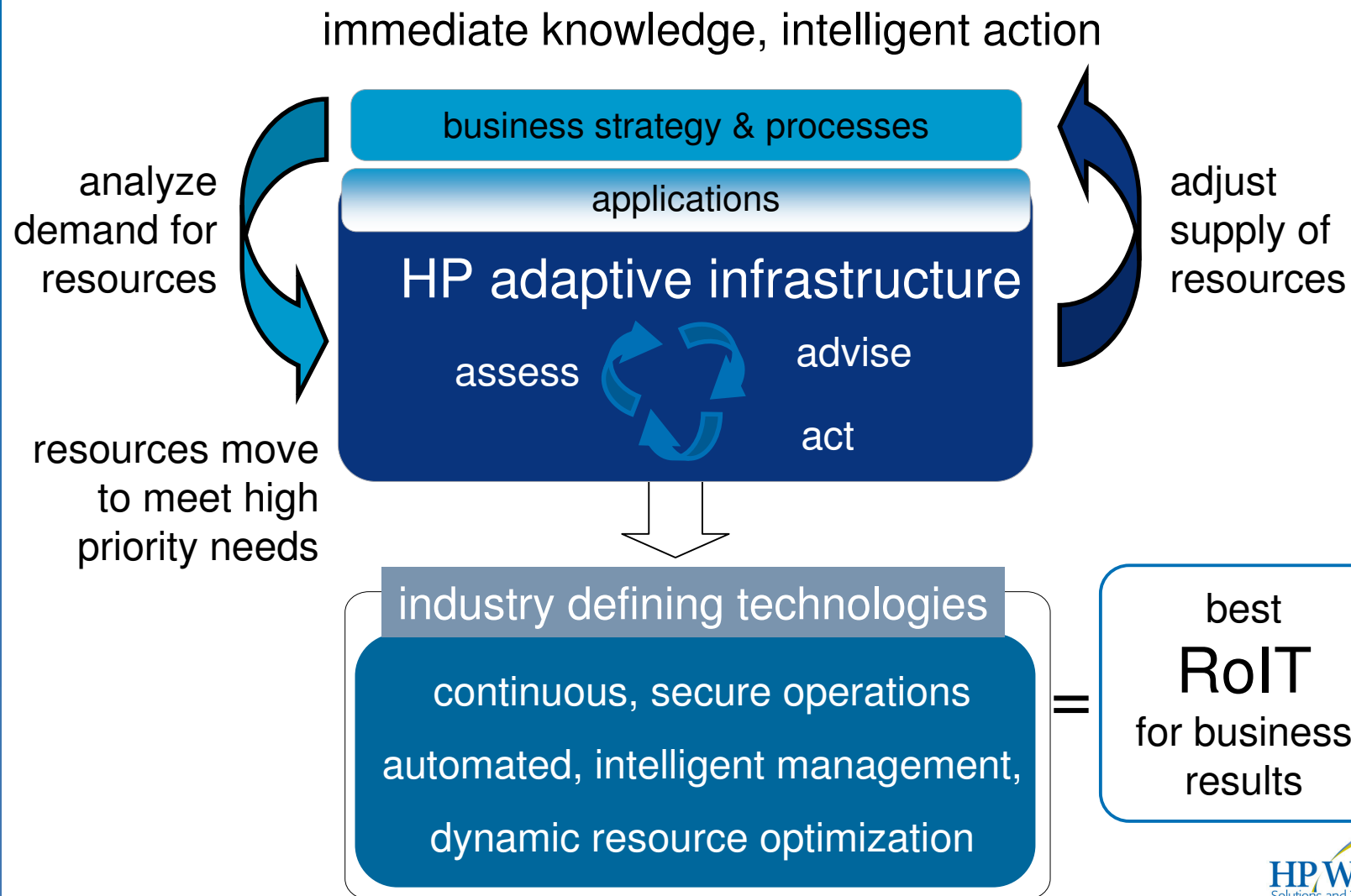
Adaptive Enterprise

= Business and IT Synchronized to Capitalize on Change

- + Standards Based Computing
- + Multi-OS
- + Flexible, Adaptable, Reliable
- + Management Simplicity
- + Dynamic Allocation of Virtualized Resources to Changing Work Loads
- + Utility Pay-per-use Business Model



Business agility requires an HP adaptive infrastructure



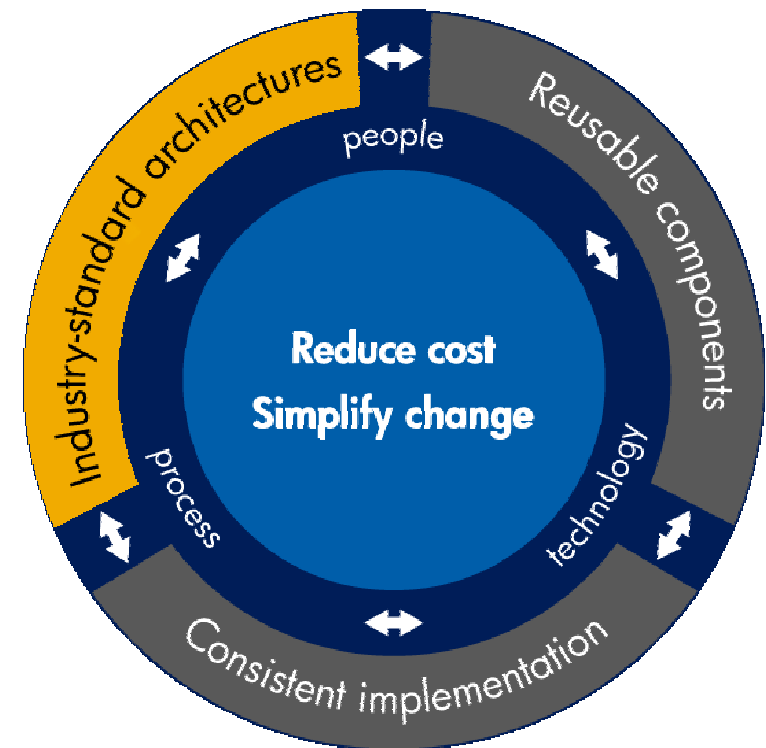
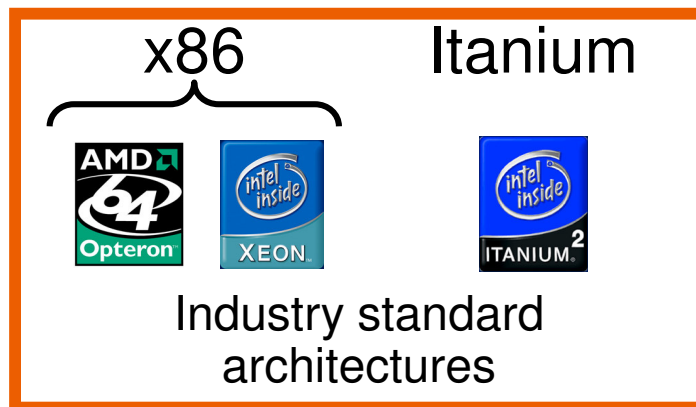
An Adaptive Enterprise Starts with Standards



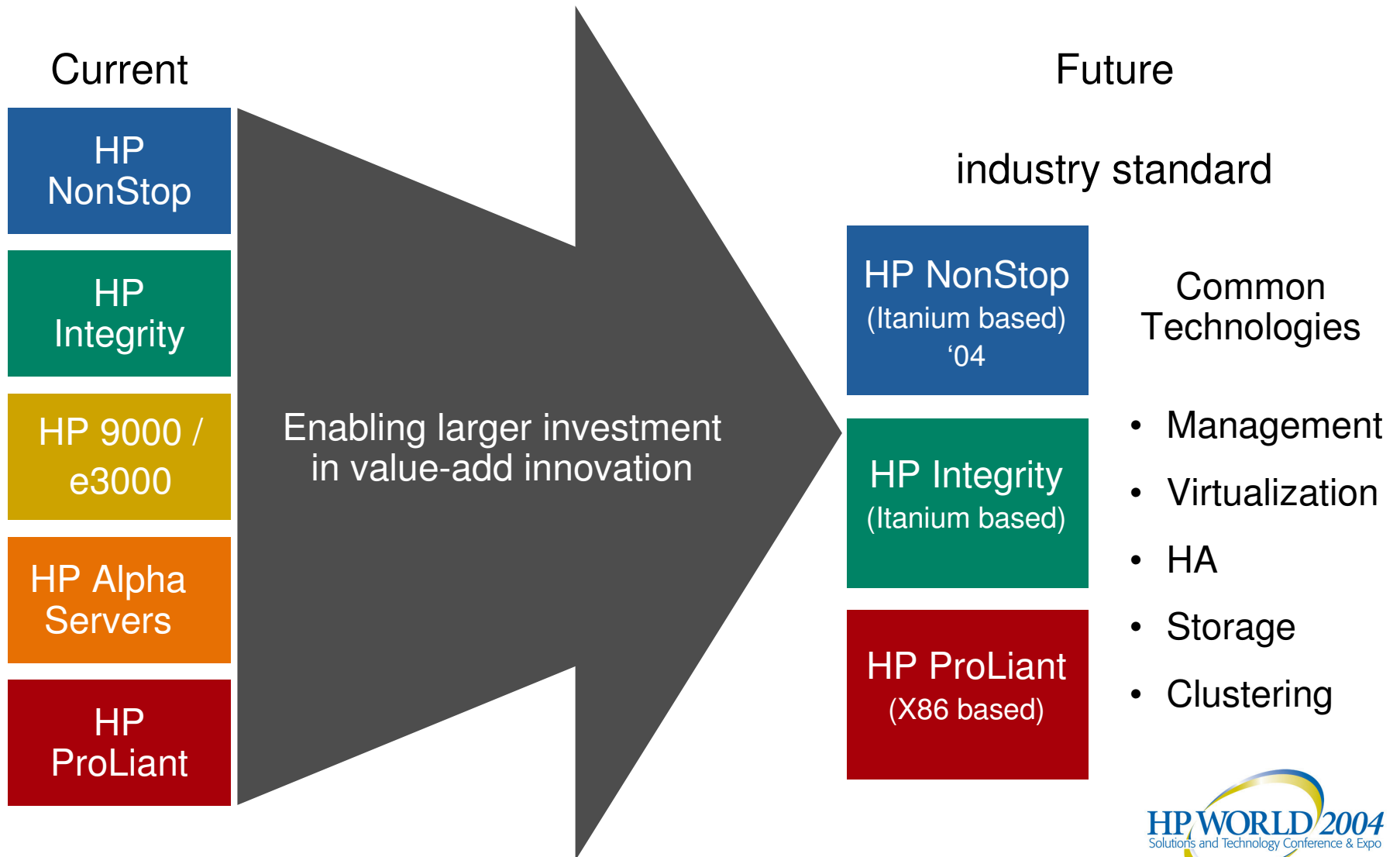
HP is:

- Committed to providing the best in industry standard components
- Providing more customer choice without compromise
- Investing in industry standards and focused innovation

Complementary, modular approach based on two standard architectures

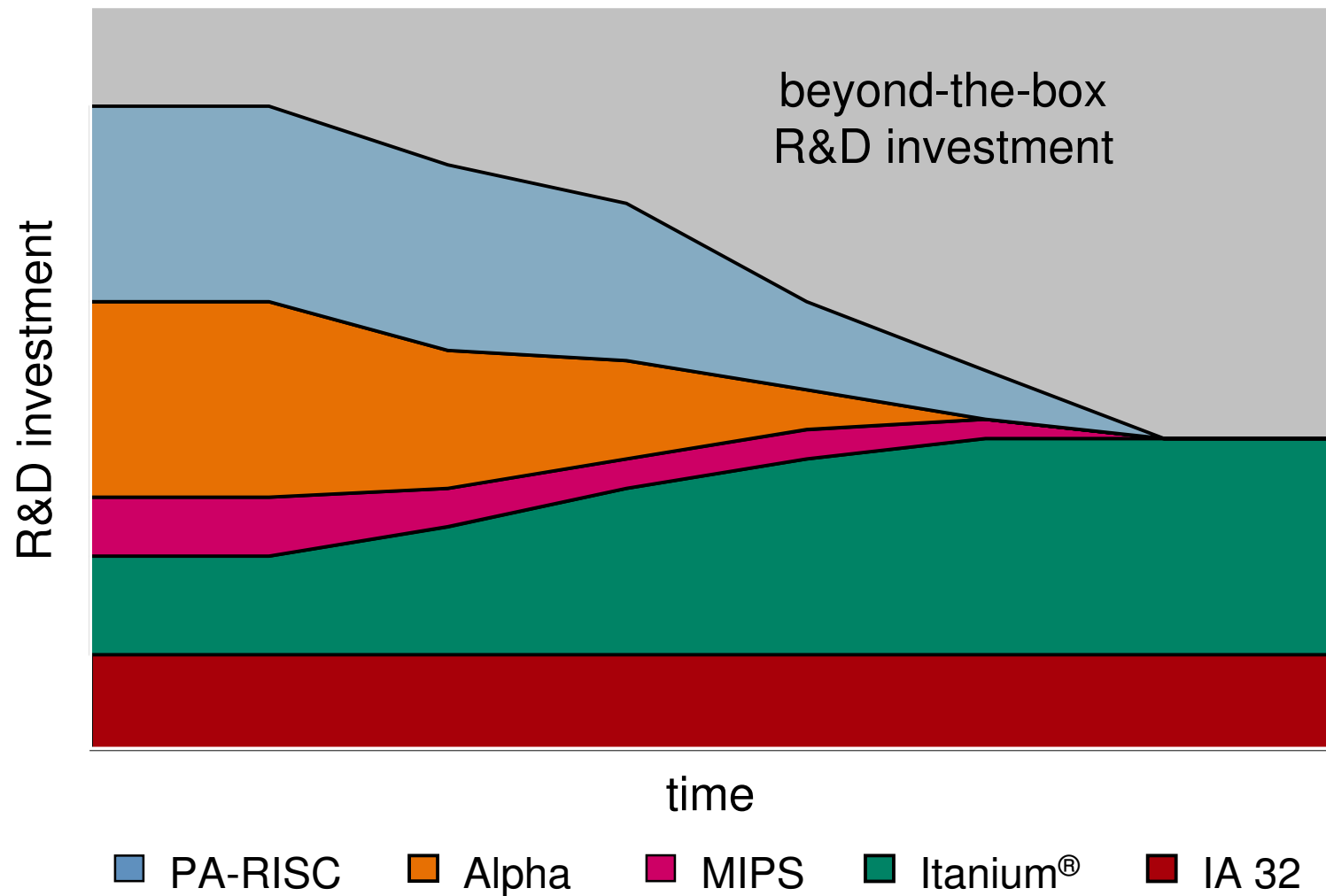


Moving to 3 leadership product lines – built on 2 industry standard architectures



Investing beyond the box

Focused innovation



Why a “Standards” Approach?

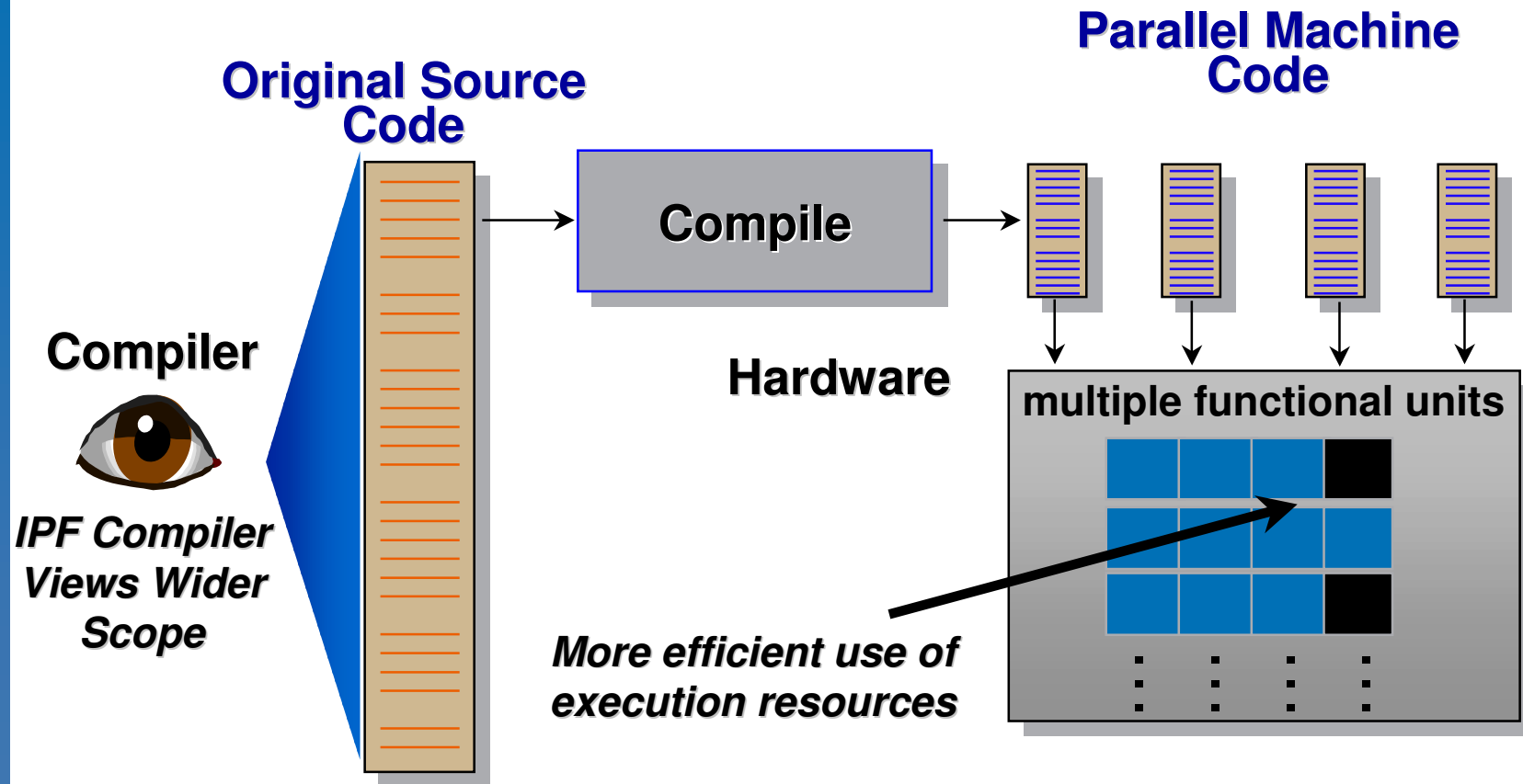
EPIC → Intel Itanium

- Moore’s 2nd Law → Fab Economics
- Customer Contribution / Market Trends
 - Shift in Investment Focus
- Flexibility of multi-OS, vs. Single Use Platform
- Enables partnering to create best-in-class solutions
- Drives leadership cost structures

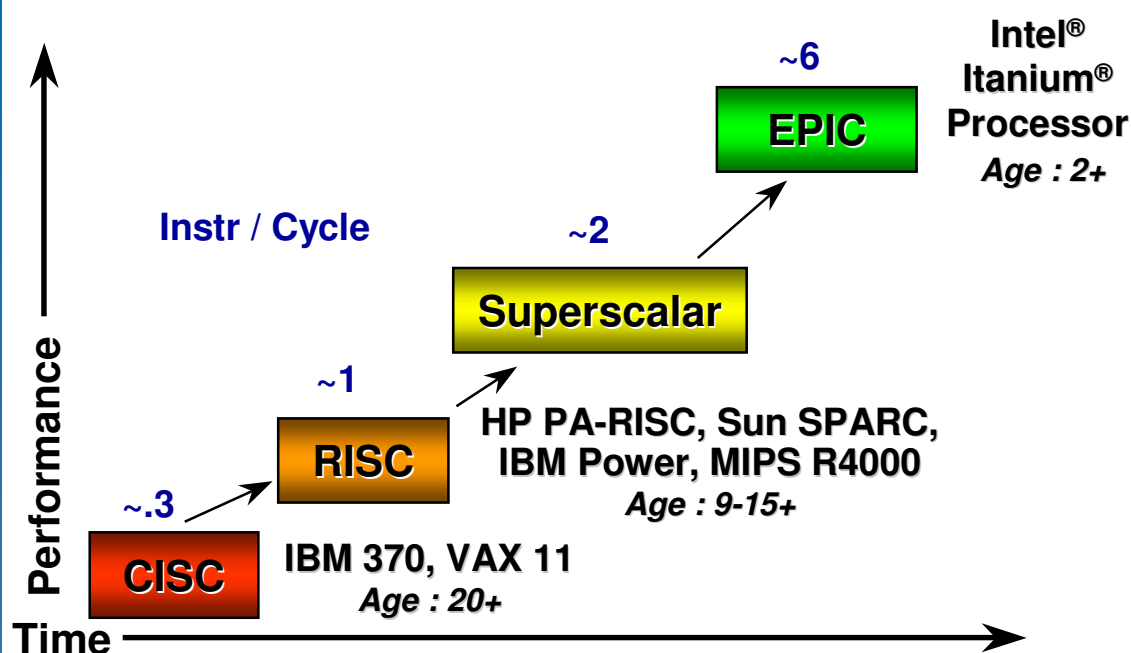
Why a New Architecture?

- New workloads relentlessly demand greater application performance, at lower price/performance
- The need to overcome the limitations of RISC
 - RISC (and CISC) architectures based on Von Neumann model; processing must appear to be done sequentially
 - Exponential increase in logical control complexity of Out-of-Order processing
 - Increased circuit overhead to take RISC to greater levels of parallel execution not economical (cost increase > performance increase)
- Recognize that for processor architecture to sustain execution of multiple instructions per cycle, compiler must explicitly schedule instructions
- Requirement for much greater number of architected registers to expose the parallelism
- Increasing demand on processor fault management and scalability to meet the needs of enterprise data centers

Itanium/EPIC Architecture: Explicit Parallelism



Intel Itanium Architecture: Designed for Business Critical Computing



Next Enterprise Architecture

Larger and more demanding workloads require new approach:

- Designed for 64-bits from the ground up
- Architected for performance, scalability, and business critical availability

Performance through parallelism

- Built-in instruction-level parallelism
- Issue ports and execution units support up to twice as many instrs/clock cycle
- Maturity curve narrows clock speed gap over time

Massive on-chip resources

- 128 general registers, 128 floating point registers, 8 branch (vs 16 on x86)
- Fewer memory accesses (loads/stores) on complex workloads

Beating the memory latency gap & shorter pipeline

- Very large virtual and physical address spaces
- Shorter memory pipeline
- Latency avoidance
- Predication of instruction execution
- Data and control speculation

Business Critical Availability

- Machine Check Architecture
- Security: sophisticated ring protection and buffer overflow protection
- Protected data paths
- Failure mode analysis

Architecture Success Factors



Success Factors

- **Technology :**

- Semiconductor manufacturing
- Architecture
- Design

- **Economics**

- **Industry Adoption**

- Applications
- Systems (wide range low to high end)
- Industry ecosystem
 - Supply chain
 - Supporting technology

Status

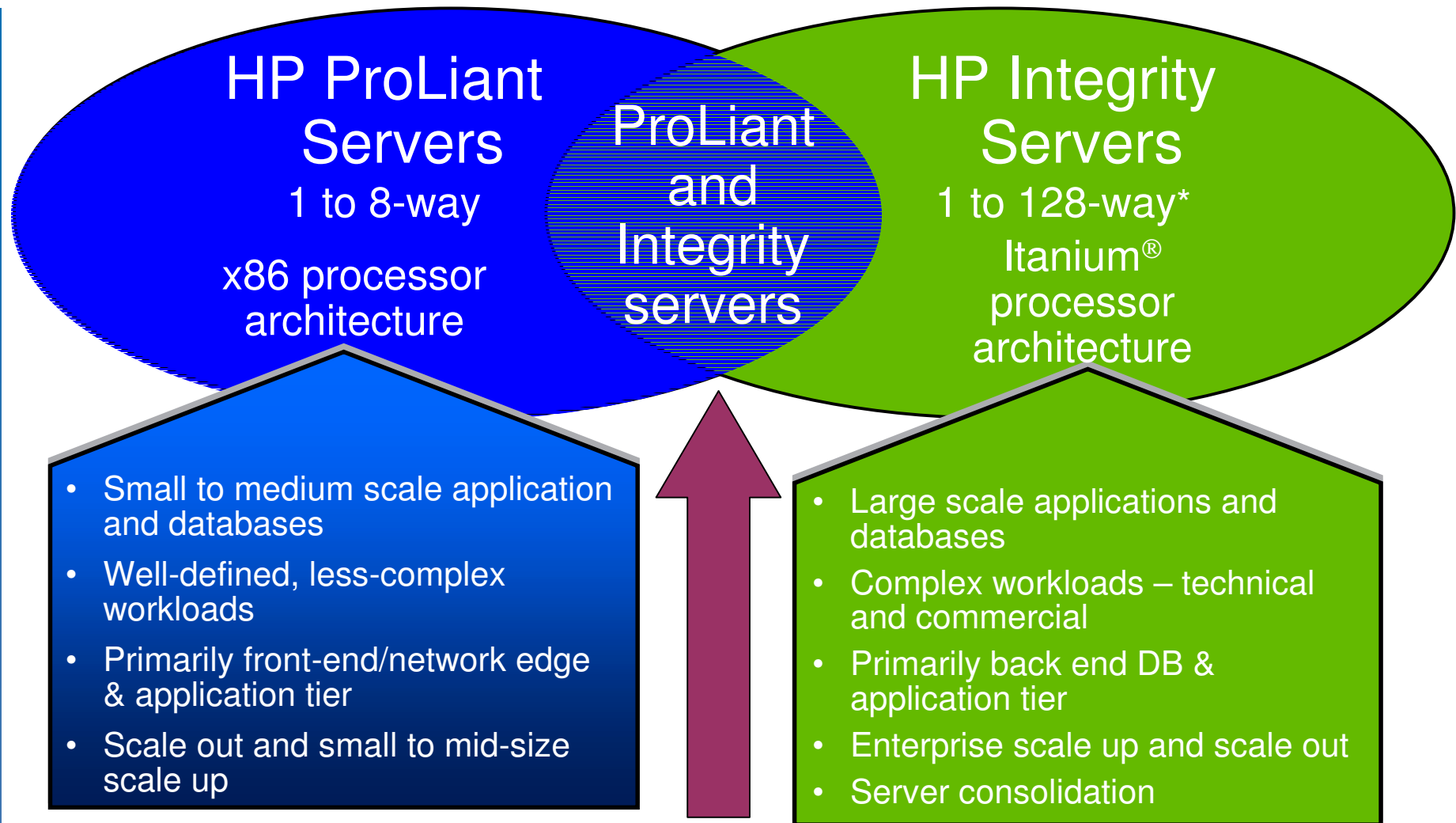
Combination of investment and capability unmatched in the industry

Standards approach drives volume and cost, leverages best-in-class solutions, enables partnership / collaboration

>2200 apps today, rate of new apps increasing;
~40+ systems from 10 server suppliers (every major company except Sun);
Expect Itanium proc volume > any RISC in '05-'06.



Customer choice



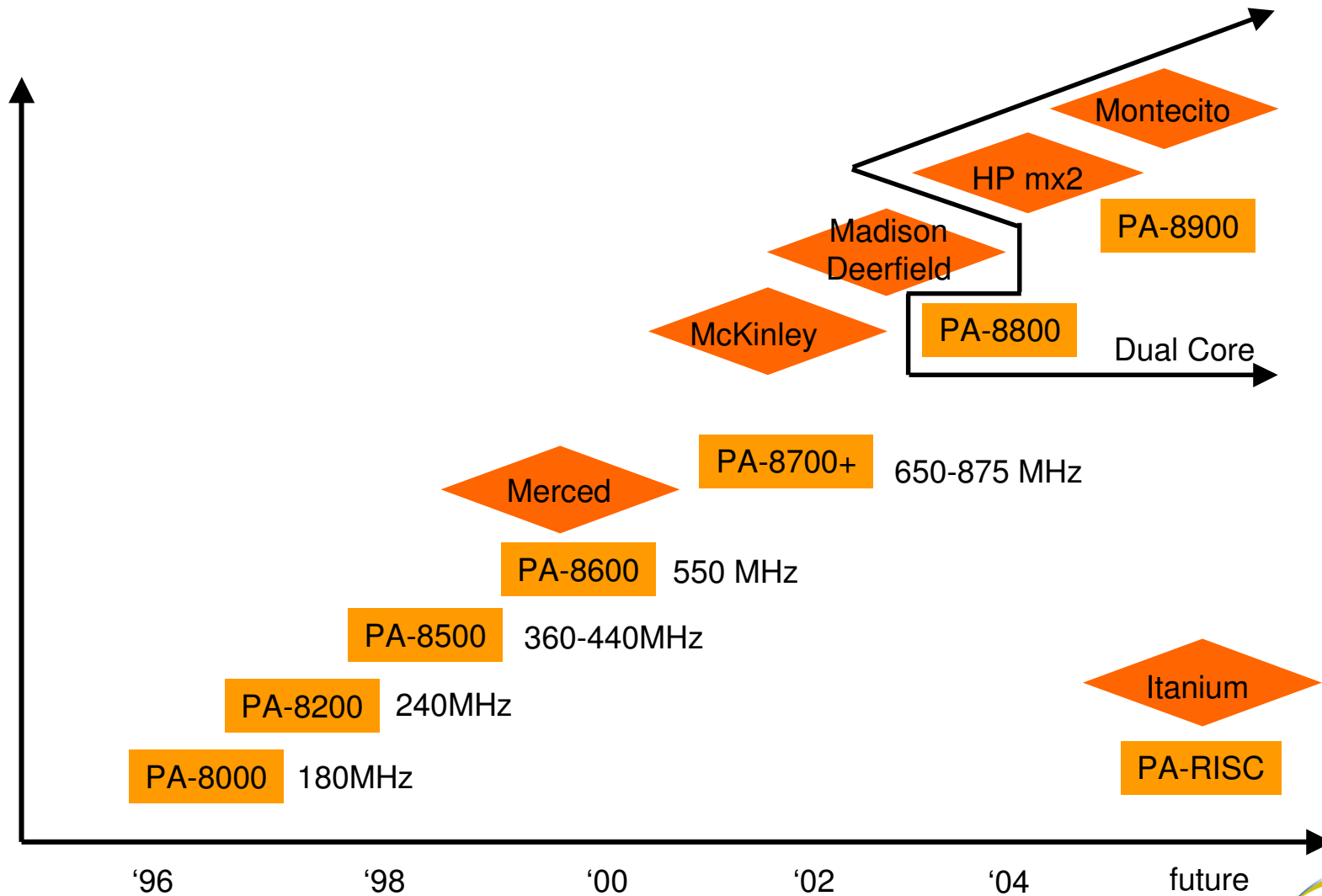
Customer-specific needs driven

Agenda

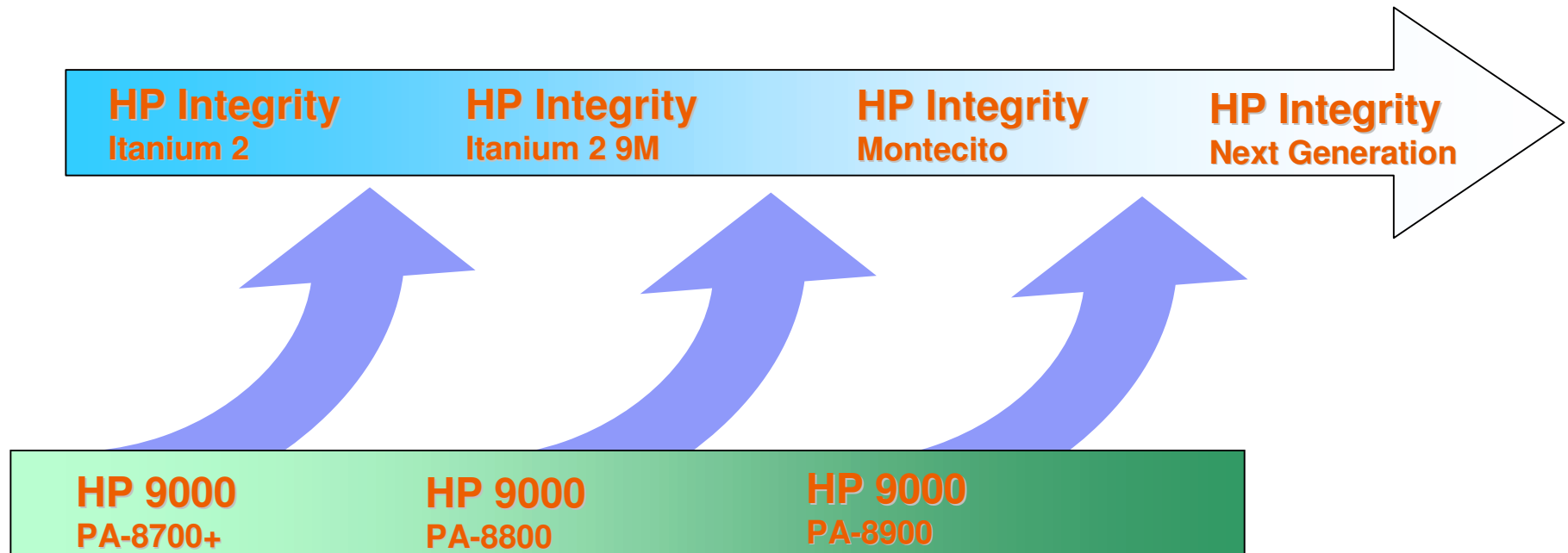
- Integrity/Itanium Strategy
- PA-Risc & Alpha Transition
- Integrity Product Lineup
- Integrity Platform Futures

Microprocessor Roadmap

PA-RISC and Itanium



HP 9000 to Integrity migration



- Customers pick the time that is right for them
- Simple evolution (In-box upgrades)
- Superior investment protection
- Tools, partners & services available to help customers evolve

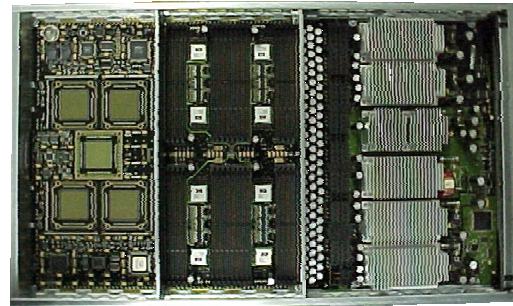
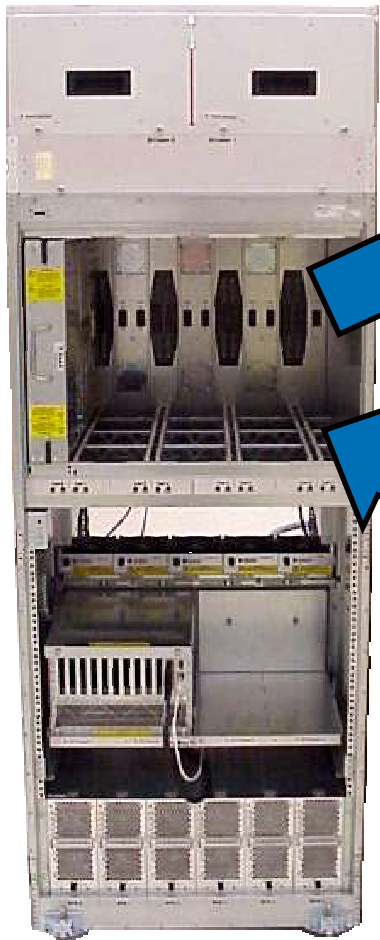


PA leverage from Itanium simplifies transition

- HP's relationship with Intel allowed us to leverage the Itanium CPU bus and form factor for PA-RISC
- HP first implemented this standard with the PA-8800
 - Allows HP to develop one set of chipsets, boards, and systems for both architectures
 - Makes it extremely simple to switch architectures
 - Simply remove the PA CPUs from the boards, replace with Itanium CPUs, and flash the firmware.
 - Nothing else in the system changes (boards, chassis, memory, power, cooling, manageability, etc.)

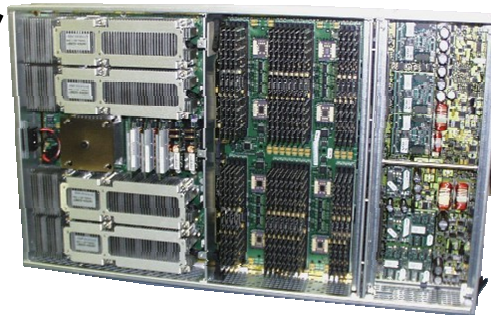


Cell board swap converts from PA8600-8700+ to PA-8800/8900, and all Itanium® CPUs



Superdome "Yosemite"
cell board for PA
8600, 8700, and
8700+

The same (existing) chassis is used for all products.



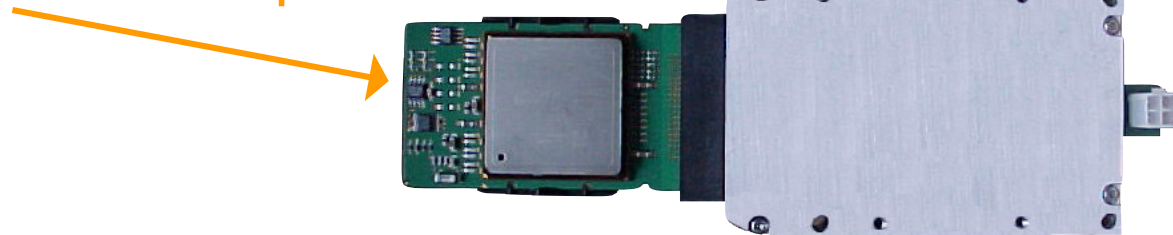
Superdome "Pinnacles"
cell board for PA
8800, 8900, and all
Itanium® processors



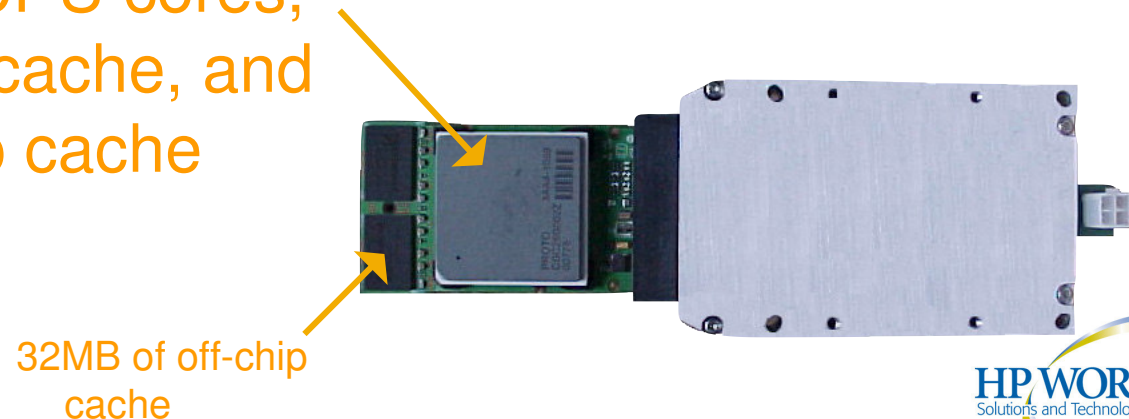
Superdome is shown, but an identical path exists for the rp8400 and rp7410.

PA leverage from Itanium simplifies transition

Itanium2® CPU module from
Intel containing one CPU core
and up to 6MB of on-chip cache

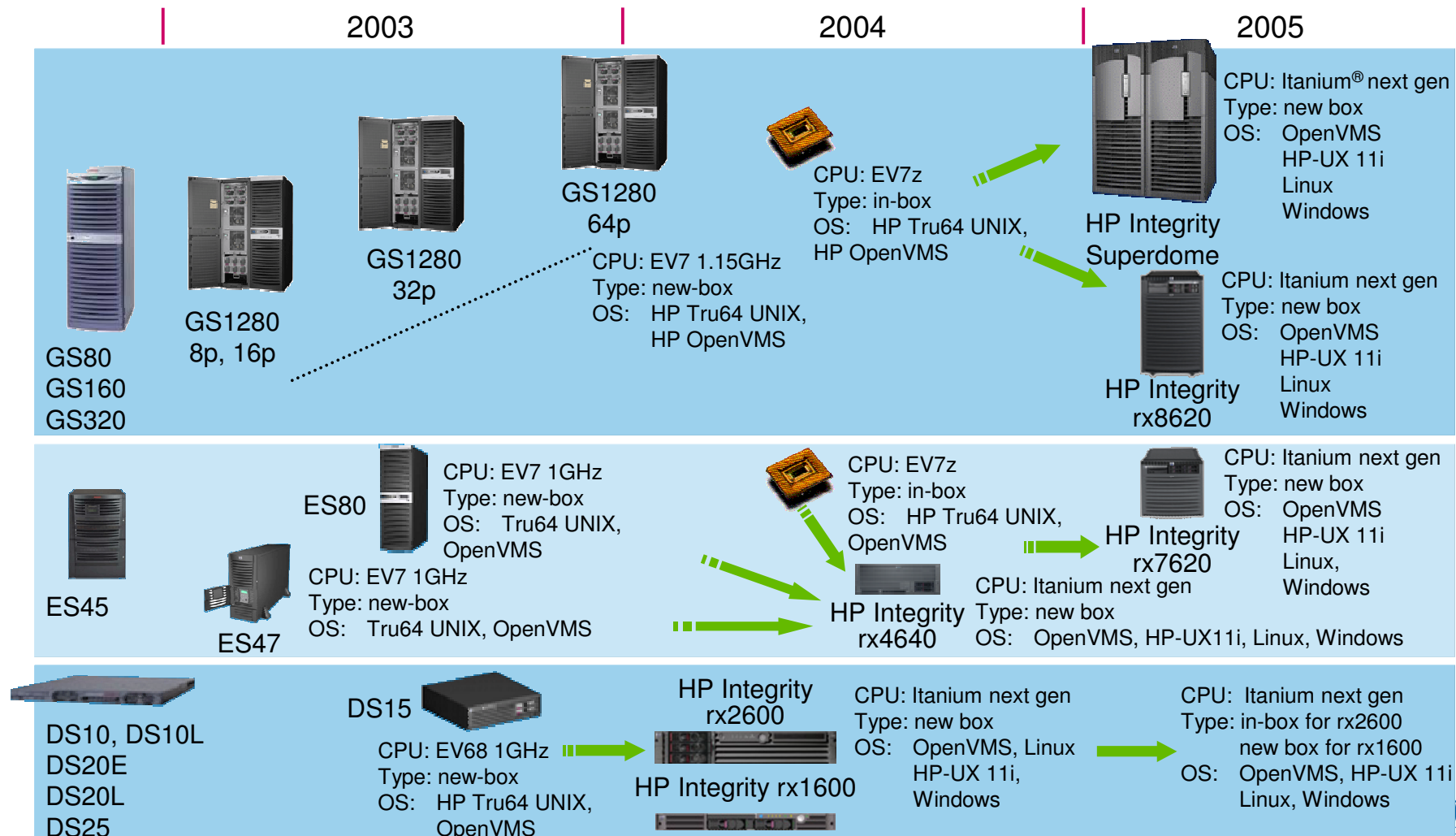


PA-8800 CPU module from HP
containing two CPU cores,
3MB of on-chip cache, and
32MB of off-chip cache



HP AlphaServer evolution

Sales at least until 2006, with support at least until 2011



Subject to change without notice

Agenda

- Integrity/Itanium Strategy
- PA-Risc & Alpha Transition
- Integrity Product Lineup
- Integrity Platform Futures



HP Integrity servers

Max. CPUs

64

HP Integrity
Superdome



**Up to 64-way
scalability and hard
partitioning capability
for leading
consolidation**

- Up to 64 Intel® Itanium® 2 processors
- Up to 512 GB memory
- 192 PCI-X slots (with SEU)
- Up to 16 hard partitions

16

HP Integrity rx8620



**16-way scalability
and hard partitioning
capability for
consolidation**

- 2- to 16-way Intel Itanium 2 processors
- Up to 128 GB memory
- 32 PCI-X slots (with SEU)
- Up to 4 hard partitions
- 2 servers per 2m rack

8

HP Integrity rx7620



**8-way flexibility with
high performance,
density, and
partitioning
capabilities**

- 2- to 8-way Intel Itanium 2 processors
- Up to 64 GB memory
- 15 PCI-X slots
- Up to 2 hard partitions
- 4 servers per 2m rack

4

HP Integrity rx4640



**4-way high-
performance servers in
ultra-dense and highly
scalable models**

- 1- to 4-way Intel Itanium 2 processors
- Up to 64 and 96 GB memory
- 6 and 10 PCI-X slots
- 10 and 5 servers per 2m rack

2

HP Integrity rx2600
& rx1600



**2-way ultra-dense,
power-packed server
redefines entry-level
computing**

- 1- to 2-way Intel Itanium 2 processors
- Up to 24 GB memory
- 4 PCI-X slots
- 20 servers per 2m rack

Microsoft
Windows Server 2003



OpenVMS

HP-ux11i
Version 2

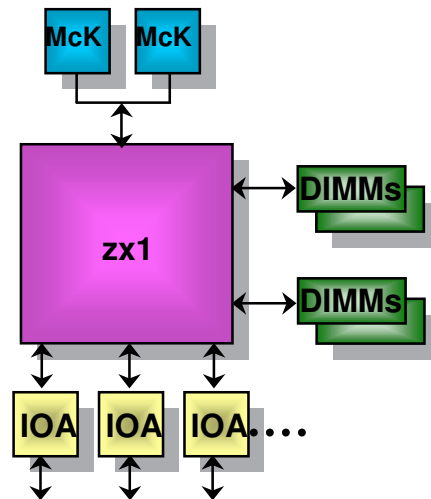
HP zx1 chipset

1-2 Way Configuration

System Bus
 128 bits wide
 200MHz/400 MT/s
 6.4 GB/s

Memory
 266 Mhz DDR
 lowest latency
 8.5 GB/s
 “chipkill”

IO
 4 GB/s
 PCI-X/AGP Support

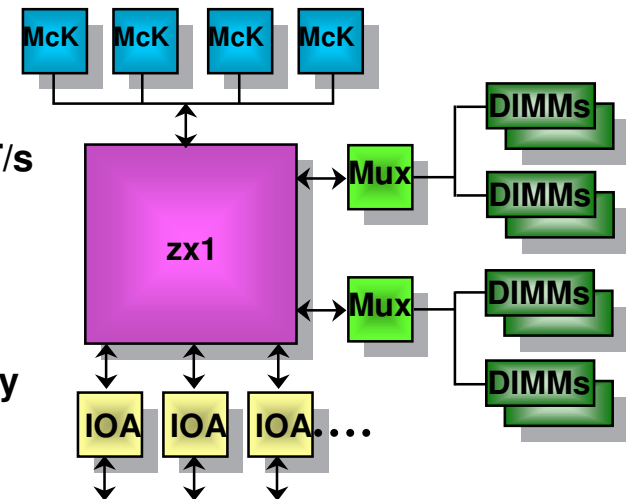


4 Way Configuration

System Bus
 128 bits wide
 200MHz/400 MT/s
 6.4 GB/s

Memory
 200 Mhz DDR
 highest capacity
 12.8 GB/s
 “chipkill”

IO
 4 GB/s
 PCI-X 133Mhz/64bit



HP's zx1 chipset delivers industry leading memory latency and bandwidth, I/O capability, and resilience features for Intel's Itanium2 processor family

rx1600

- One or two Itanium2 processors
 - Deerfield low-voltage, low-power CPUs
- 2 independent PCI-X slots
- 200 MHz processor bus
 - 6.4 GB/s of bandwidth
- Advanced memory technology
 - 8 memory DIMM slots for DDR SDRAM
 - 16 GB of memory
- System Package
 - 1U, 27 inches deep
 - 2 hot-swap bays for 1" hard disks, 1 built-in DVD ROM
 - built-in dual lan



rx2600

- 2 CPU sockets
 - 2 way Itanium2 Madison (rx2600)
- 4 independent PCI-X slots
- 200 MHz processor bus
 - 6.4 GB/s of bandwidth
- Advanced memory technology
 - 12 memory DIMM slots → 24GB of memory
 - 8.5 GB/s of memory bandwidth (peak)
 - “chipkill” multi-bit memory error correction
- System Package
 - 2U, 26 inches deep
 - 3 hot-swap bays for 1” hard disks, 1 built-in DVD ROM
 - Optional redundant power supplies and cords



rx4640

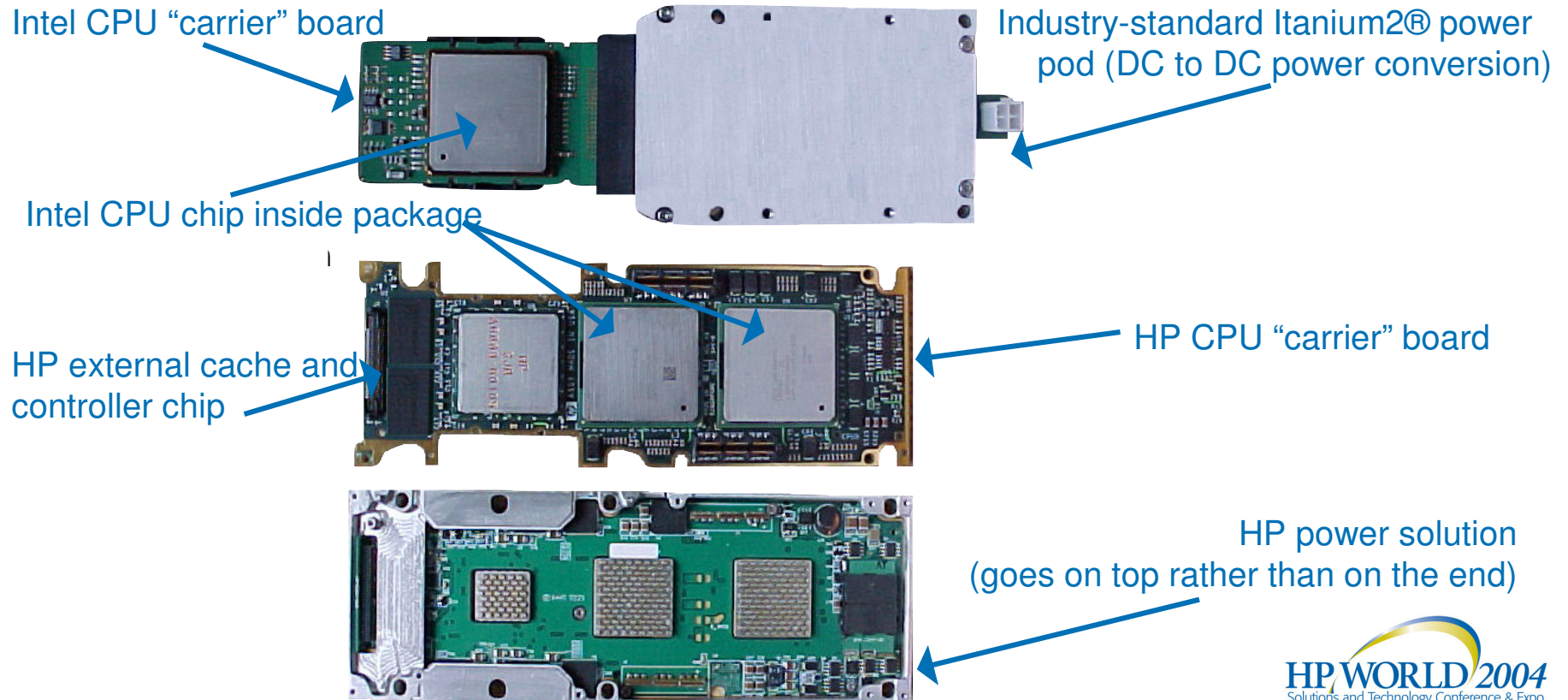
- 4 CPU sockets
 - 4 way Itanium2 Madison (rx4640)
 - 8 way Itanium2 mx2 module
- HP zx1 chipset
 - 12.8 GB/s of memory bandwidth
 - “chipkill” multi-bit memory error correction
- Offered with 16 or 32 DDR DIMM slots
 - 1GB and 2GB DIMMs available
- System Package
 - 19” rack, 4U form factor → 2X density over existing rx5670
 - 2 hot-swap bays for 1” hard disks, built-in DVD ROM and LS-240 drive
 - Optional redundant power supplies and cords



“Inventing” a dual core Itanium® CPU



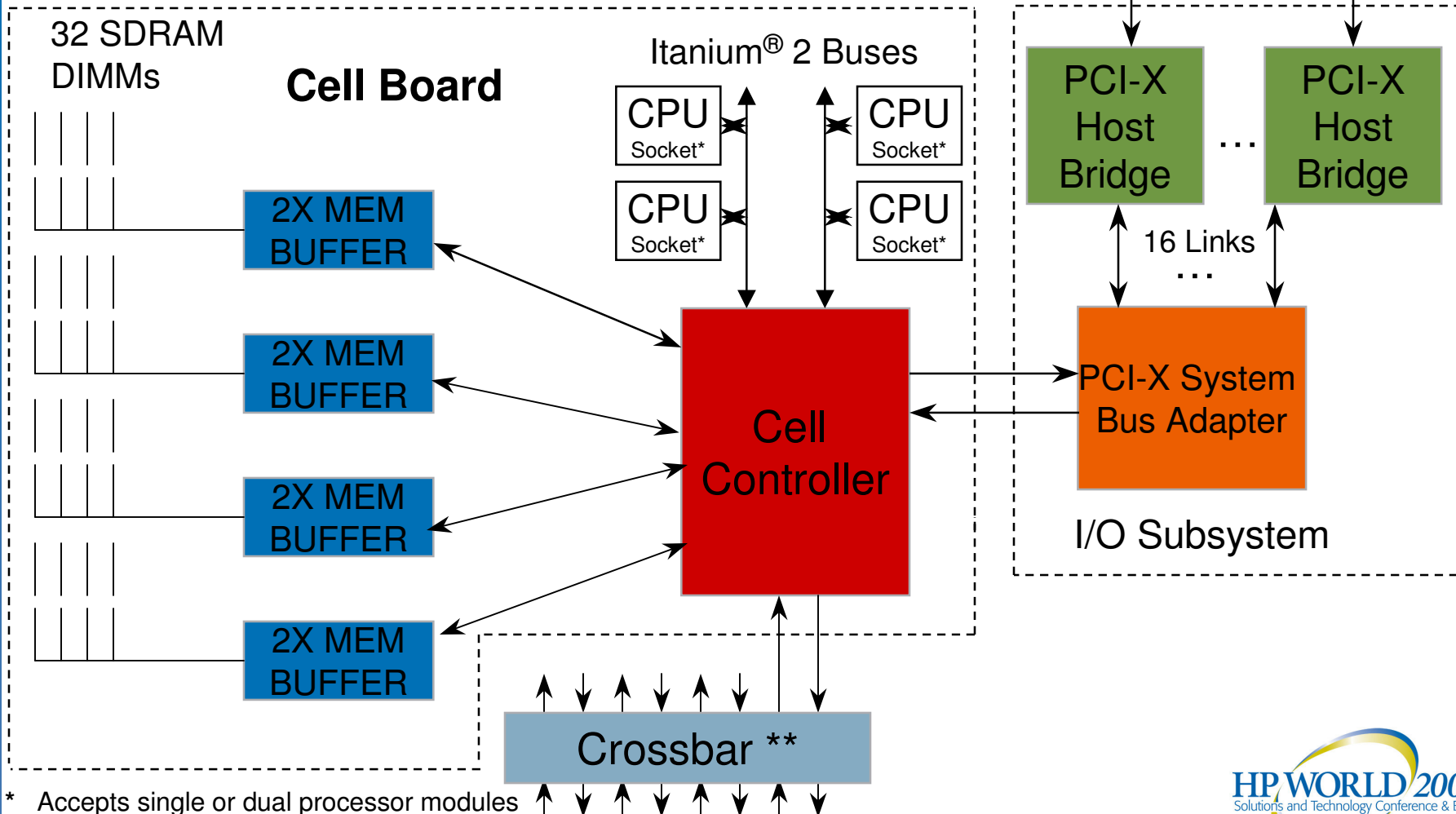
- The standard Intel cartridge packaging is not at maximum density
 - CPU silicon chip is in a package, on a carrier board, with power on the end
 - The basic chip and package could be packed much more densely



sx1000 chipset for hp's mid-range and high end systems



Maximizes application performance from 4 to 128 processors

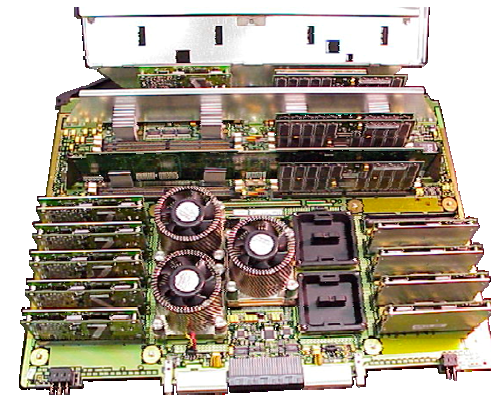
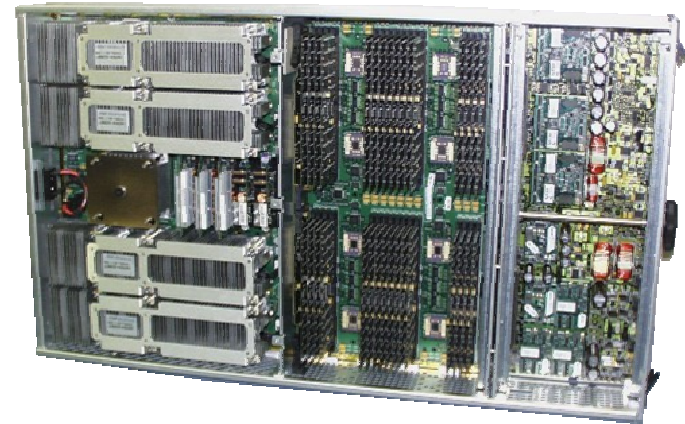


* Accepts single or dual processor modules

** Not used in 8 socket systems

Cell Boards

- 4 processor sockets
 - 2 CPU busses
- 8 or 12 I/O slots per cell
 - PCI-X (1 GB/s bandwidth)
 - Each slot is its own PCI-X bus
- Memory technology
 - 16 or 32 DIMM sites
 - “chipkill” multi-bit error correction
- Cache Coherent Interconnect
 - Connects to other cells to form partitions



rx7620

- 8 CPU sockets
 - 8 way Itanium2 Madison (rx7620)
 - 16 way Itanium2 mx2 module
- Same cellular technology as Superdome
 - Performance, partitioning, etc.
 - 32 DIMM slots → 64 GB of memory
 - “chipkill” multi-bit error correction
 - 16 PCI I/O slots
- System Package
 - 10U, 28.5 inches deep
 - 4 hot-swap hard disks bays, 1 removable media bay
 - 2N redundant power supplies
 - Optional redundant power cords



rx8620

- 16 CPU sockets
 - 16 way Itanium2 Madison (rx8620)
 - 32 way Itanium2 mx2 module
- Same cellular technology as Superdome
 - Performance, partitioning, etc.
 - 64 DIMM slots → 128 GB of memory
 - “chipkill” multi-bit error correction
 - 16 PCI I/O slots
- System Package
 - 17U, 28.5 inches deep
 - 4 hot-swap hard disks bays, 2 removable media bays
 - N+1 redundant power supplies
 - Optional redundant power cords
- Optional I/O expander
 - 16 additional PCI I/O slots
 - 4 more hot-swap disks and 2 more removable media bays

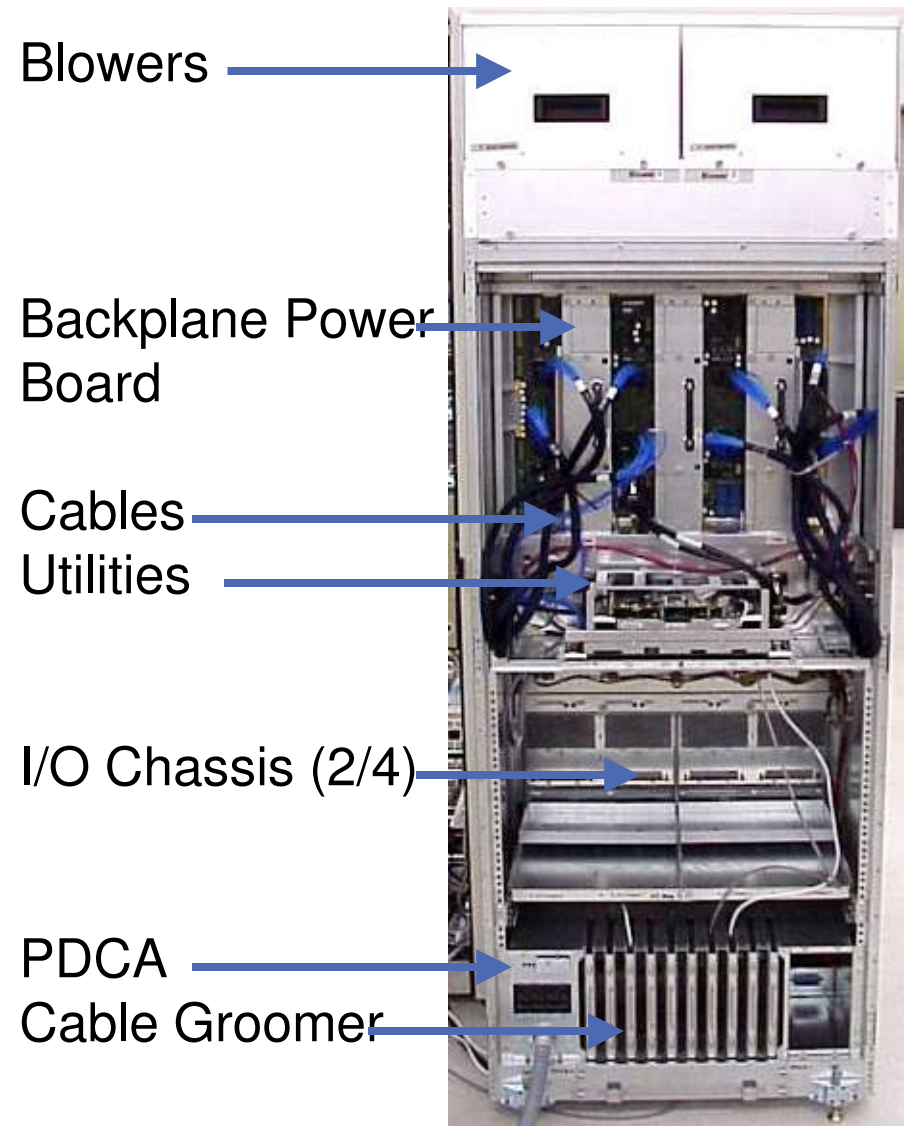
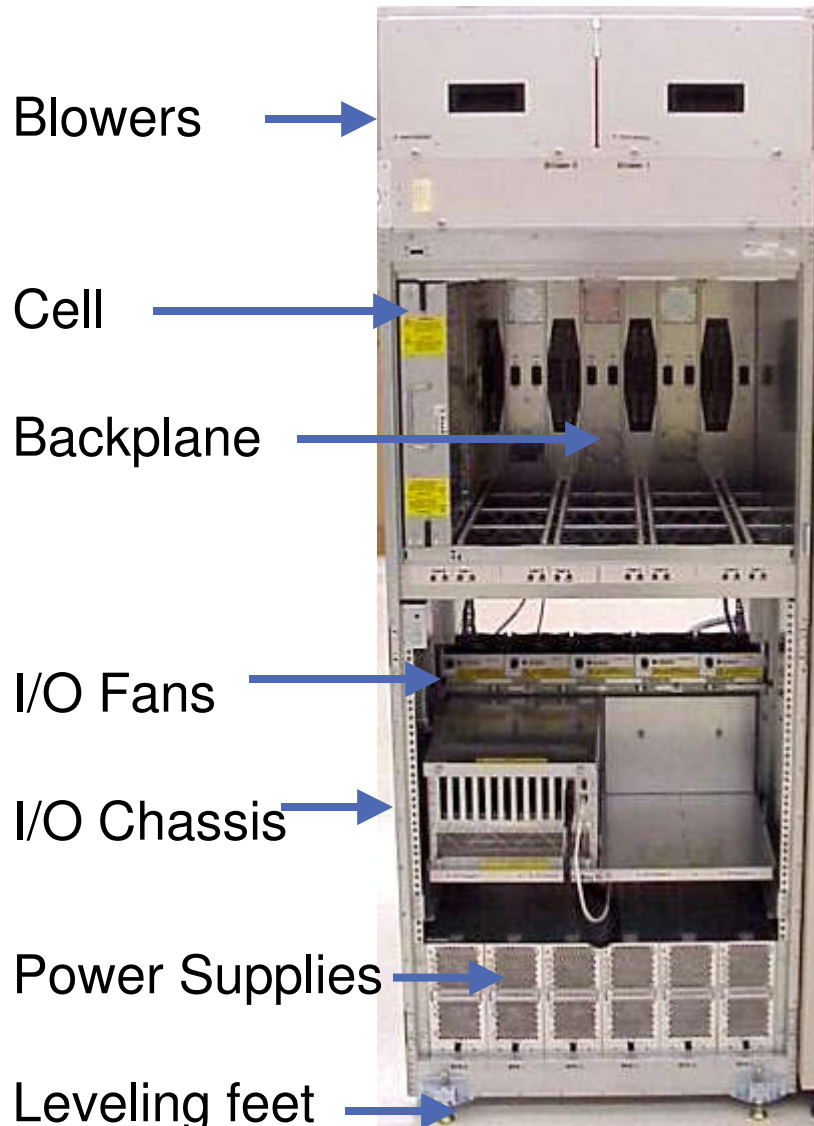


Superdome

- 64 CPU sockets
 - 64 way Itanium2 Madison (dual cabinet)
 - 128 way Itanium2 mx2 module
- sx1000 chipset technology
 - 512 DIMM slots → up to 1 TB of memory
 - “chipkill” multi-bit error correction
 - Hard partitioning
 - Up to 192 PCI-X I/O slots
- System Package
 - Custom cabinet
 - N+1 redundant power supplies
 - Optional redundant power cords



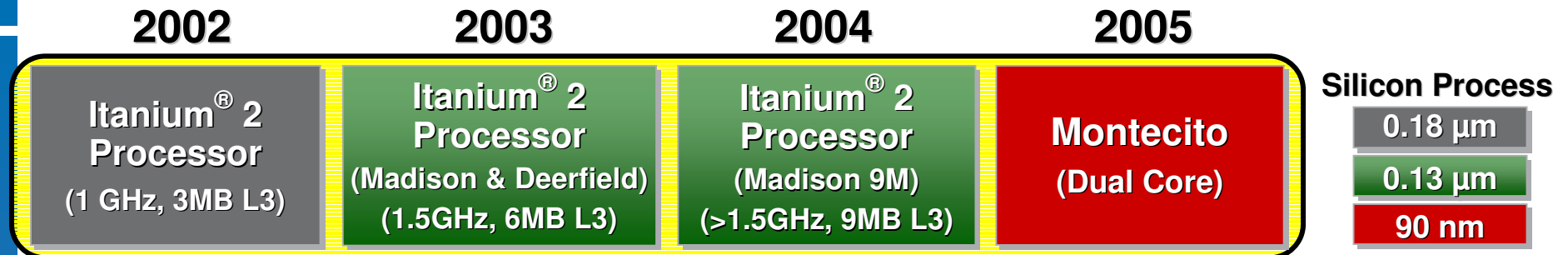
Superdome System View



Agenda

- Integrity/Itanium Strategy
- PA-Risc & Alpha Transition
- Integrity Product Lineup
- Integrity Platform Futures

Itanium® Processor Family Roadmap



- **Itanium® 2 Processor (Madison) – shipping across entire product line**
- **Itanium® 2 platform maintains same socket, bus and software compatibility**
- **Intel will enhance Itanium® 2 processor (Madison) with larger 9M L3 cache**
- **Montecito processor will enable dual-core technology and enhanced micro-architecture**






Roadmap maintains world class performance



HP Integrity and HP 9000 Server Roadmap



Revision 4.5 July-04

Current offering		2004		2005	2006
 4-128P	HP 9000 Superdome			CPU: PA-8900 (dual-CPU) OS: HP-UX 11iv1, v2, v3*	New Chipset CPU: PA-8900 OS: HP-UX 11iv1, v2, v3 DDR-II
	HP Integrity Superdome	CPU: mx2 module OS: HP-UX11iv2, Windows	CPU: Itanium2 9M OS: HP-UX11iv2, Windows, Linux*	CPU: Itanium2 "Montecito" New Chipset OS: HP-UX 11iv2, v3* DDR-II Windows, Linux, OpenVMS	PCI-E
 2-16P 2-32P	HP 9000 rp7410-8, rp8400-16 rp7420-16, rp8420-32			CPU: PA-8900 (dual-CPU) OS: HP-UX 11iv1, v2, & v3*	New Chipset CPU: PA-8900 OS: HP-UX 11iv1, v2, v3 DDR-II
	HP Integrity rx7620-16, rx8620-32	CPU: mx2 module OS: HP-UX11iv2, Windows	CPU: Itanium2 9M OS: HP-UX11iv2, Windows, Linux*	CPU: Itanium2 "Montecito" New Chipset OS: HP-UX 11iv2, v3* DDR-II Windows, Linux, OpenVMS	PCI-E
 1-8P	HP 9000 rp4440-8			CPU: PA-8900 (dual-CPU) OS: HP-UX 11iv1, v2, v3*	New 8p Server & Chipset CPU: Itanium2 "Montecito" OS: HP-UX, Windows, Linux, OpenVMS DDR-II PCI-E
	HP Integrity rx4640-8	CPU: mx2 module OS: HP-UX11iv2, Windows, OpenVMS*	CPU: Itanium2 9M OS: HP-UX11iv2, Windows, Linux*, OpenVMS	CPU: Itanium2 "Montecito" OS: HP-UX 11iv2, v3* Windows, Linux, OpenVMS	
 1-4P	HP 9000 rp3440-4			CPU: PA-8900 (dual-CPU) OS: HP-UX 11iv1, v2, v3*	New 4p Server & Chipset CPU: Itanium2 "Montecito" OS: HP-UX, Windows, Linux, OpenVMS DDR-II PCI-E
	HP Integrity rx2600-2			CPU: Itanium2 9M OS: HP-UX11iv2, Windows, Linux*, OpenVMS	
 1-2P	HP Integrity rx1600-2			CPU: Low voltage Itanium2 (+) OS: HP-UX 11iv2, v3*, Windows, Linux, OpenVMS	CPU: Next Gen & Chipset Low voltage Itanium2 OS: HP-UX, Windows, Linux, OpenVMS DDR-II PCI-E

Timeframes not to scale

All upgrades "in-box" except as noted

Plans subject to change

New Chassis Intro.

PCI-Express

DDR-II Memory

*Not available at initial processor release

Solutions and Technology Conference & Expo

Industry CPU trends

- Shift from micro-pipelining and the frequency race to more cores per die
- Multi-threading
- Larger on-chip caches
- Increased bus frequencies, higher bandwidths, link (point to point) technologies

HP chipset futures

- Continued differentiation enabling leadership system performance
- Increases in memory bandwidth, capacity
- Improved IO and system fabric bandwidths
- Keeping up with industry standards
 - DDR-II SDRAM technology
 - PCI-Express technology
- Continued focus on reducing access latency
- Additional system reliability and resiliency features
- And more...

Tying It All Together

The Future of Computing is:

Standards-Based, Virtualized Resources, Flexible, Self-Adaptive, Multi-OS Environment, Highly Available, Utility

This future is enabled by HP

Itanium Processors / Standards Technology



Leadership Systems: Leadership Performance, Price/ Performance, Resource Partitioning, Reliability, Fault Management, Availability,



Multi-OS, Common Manageability



Dynamic Re-allocation of Virtualized, Self-managed Data Center Resources



Adaptive Enterprise



Best RoIT for our Customers

HP WORLD 2004

Solutions and Technology Conference & Expo

Co-produced by:



RECOMMENDED TRAINING VENUE FOR THE
HP Certified Professional

